# Product End-of-Life Disassembly Instructions

**Product Category:** Monitors and Displays

**Marketing Name / Model**
[List multiple models if applicable.]
HP Z27q 27-inch IPS 5K Display

**Purpose:** The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

## 1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

<table>
<thead>
<tr>
<th>Item Description</th>
<th>Notes</th>
<th>Quantity of items included in product</th>
</tr>
</thead>
<tbody>
<tr>
<td>Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)</td>
<td>With a surface greater than 10 sq cm USB BD, IF BD, POWER BD, FK BD</td>
<td>4</td>
</tr>
<tr>
<td>Batteries</td>
<td>All types including standard alkaline and lithium coin or button style batteries</td>
<td>0</td>
</tr>
<tr>
<td>Mercury-containing components</td>
<td>For example, mercury in lamps, display backlights, scanner lamps, switches, batteries</td>
<td>0</td>
</tr>
<tr>
<td>Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm</td>
<td>Includes background illuminated displays with gas discharge lamps Panel</td>
<td>1</td>
</tr>
<tr>
<td>Cathode Ray Tubes (CRT)</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Capacitors / condensers (Containing PCB/PCT)</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height</td>
<td></td>
<td></td>
</tr>
<tr>
<td>External electrical cables and cords</td>
<td>USB cable, DP cable, Power cord</td>
<td>4</td>
</tr>
<tr>
<td>Gas Discharge Lamps</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Plastics containing Brominated Flame Retardants</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner</td>
<td>Include the cartridges, print heads, tubes, vent chambers, and service stations.</td>
<td>0</td>
</tr>
<tr>
<td>Components and waste containing asbestos</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Components, parts and materials containing refractory ceramic fibers</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Components, parts and materials containing radioactive substances</td>
<td></td>
<td>0</td>
</tr>
</tbody>
</table>
2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

<table>
<thead>
<tr>
<th>Tool Description</th>
<th>Tool Size (if applicable)</th>
</tr>
</thead>
<tbody>
<tr>
<td>Description #1 SCREW DRIVER(PHILLIPS HEAD)</td>
<td>#0</td>
</tr>
<tr>
<td>Description #2 SCREW DRIVER(PHILLIPS HEAD)</td>
<td>#1</td>
</tr>
<tr>
<td>Description #3 SCREW DRIVER(PHILLIPS HEAD)</td>
<td>#2</td>
</tr>
<tr>
<td>Description #4</td>
<td></td>
</tr>
<tr>
<td>Description #5</td>
<td></td>
</tr>
</tbody>
</table>

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Remove Stand Base From Display Head
2. Remove Rear Cover From Display Head
3. Remove Front Cover From Display Head
4. Remove Key Board Off From Front Cover
5. Disassemble Front Cover ASSY
6. Disassemble Rear Cover ASSY
7. Remove connector and panel
8. Take Screw(×5) Off From Chassis
9. Take Screw(x11) Off From P.C.B
10. Remove PCB from Chassis (Printed Circuit Assemblies>10cm**2)
11. Remove thermal pad frorme Chassis Cover
12. Remove heat sink, Mylar and rubber off from Chassis
13. LCD PANEL EXPLODE
14. Remove VESA Cover/slider&release button off Stand Base
15. Remove Base cover &Base Cover BKT Off stand base
16. Remove Riser lift cover off stand base
17. Remove Stand Front Cover off Stand BKT
18. Remove Stand Rear Cover Off Stand BKT

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).
HP Z27q Disassembly Process

- Steve Chou
- Mechanical Engineer
- November-03-2014
External Electric Cables Dissecting Process

1. Remove Cable From Display Head.

2. Dissecting To Complete.
Remove Stand Base From Display Head

1. Push the release button

2. Remove Stand Base From Display Head.

3. Dissecting To Complete.
Remove Rear Cover From Display Head

1. Remove four wall mount screws from display head.

2. Remove Rear Cover From Display Head.

3. Dissecting To Complete.
1. Remove connector.

2. Remove Front Cover.

3. Dissecting To Complete.
Remove Key Board Off From Front Cover

1. Take three Screws Off From Front Cover

2. Remove key board from FC
Disassemble Front Cover ASSY

Remove Power Button and Function key off from Front cover Assy
Disassemble Rear Cover ASSY

Separate mid-frame from Rear Cover Assy
Remove connector and Remove Panel

1. Remove eight tape from panel.
2. Remove seven connector
3. Remove the Panel.
Take Screw(x5) Off From Chassis

1. Take Screw(x5) Off From Chassis
2. Take Screw(x11) Off From P.C.B
Remove PCB From Chassis (Printed Circuit Assemblies>10cm**2)

3. Remove PCB off from Chassis

4. Dissecting to complete.
Remove thermal pad From Chassis Cover

1. Remove thermal pad
Remove heat sink, Mylar and rubber off from chassis

2. Take off screw off the chassis

3. Remove heat sink from the chassis

4. Remove Mylar, rubber and gasket

5. Dissecting to complete.
Remove VESA Cover, slider, release button off Stand Base

Take 7 screws off

Take 2 screws off
Remove Base Cover & Base Cover BKT Off Stand Base

Take 64 Rubbers off

Take 4 Screws off

Take 4 Screws off
Remove Riser Lift cover off Stand Base
Remove Stand Front Cover Off Stand BKT
Remove Stand Rear Cover Off Stand BKT

Take 5 Screws off